

CMPA0060025F

25 W, 20 MHz-6000 MHz, GaN MMIC Power Amplifier

Cree's CMPA0060025F is a gallium nitride (GaN) High Electron Mobility Transistor (HEMT) based monolithic microwave integrated circuit (MMIC). GaN has superior properties compared to silicon or gallium arsenide, including higher breakdown voltage, higher saturated electron drift velocity and higher thermal conductivity. GaN HEMTs also offer greater power density and wider bandwidths compared to Si and GaAs transistors. This MMIC enables extremely wide bandwidths to be achieved in a small footprint screw-down package.



PN: CMPA0060025F Package Type: 780019

Typical Performance Over 20 MHz - 6.0 GHz ($T_c = 25$ °c)

Parameter	20 MHz	0.5 GHz	1.0 GHz	2.0 GHz	3.0 GHz	4.0 GHz	5.0 GHz	6.0 GHz	Units
Gain	21.4	20.1	19.3	16.7	16.6	16.8	15.7	15.5	dB
Output Power @ P _{IN} = 32 dBm	26.9	30.2	26.3	23.4	24.5	24.0	20.9	18.6	W
Power Gain @ P _{IN} = 32 dBm	12.3	12.8	12.2	11.7	11.9	11.8	11.3	10.7	dB
Efficiency @ P _{IN} = 32 dBm	63	55	40	31	33	31	28	26	%

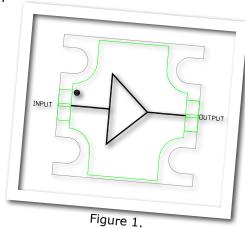
Note¹: $V_{DD} = 50 \text{ V}$, $I_{DO} = 500 \text{ mA}$

Features

- 17 dB Small Signal Gain
- 25 W Typical P_{SAT}
- Operation up to 50 V
- High Breakdown Voltage
- High Temperature Operation
- 0.5" x 0.5" total product size

Applications

- Ultra Broadband Amplifiers
- Test Instrumentation
- **EMC Amplifier** Drivers





Absolute Maximum Ratings (not simultaneous) at 25°C

Parameter	Symbol	Rating	Units
Drain-source Voltage	$V_{\scriptscriptstyle DSS}$	84	VDC
Gate-source Voltage	V_{GS}	-10, +2	VDC
Storage Temperature	T_{STG}	-65, +150	°C
Operating Junction Temperature	T,	225	°C
Maximum Forward Gate Current	I_{GMAX}	4	mA
Soldering Temperature ¹	T_{s}	245	°C
Screw Torque	τ	40	in-oz
Thermal Resistance, Junction to Case	$R_{\scriptscriptstyle{\thetaJC}}$	3.3	°C/W
Case Operating Temperature ^{2,3}	T _c	-40, +150	°C

Note:

Electrical Characteristics (Frequency = 20 MHz to 6.0 GHz unless otherwise stated; $T_c = 25$ °C)

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions
DC Characteristics						
Gate Threshold Voltage ²	$V_{(GS)TH}$	-3.8	-3.0	-2.3	V	V_{DS} = 20 V, ΔI_{D} = 20 mA
Gate Quiescent Voltage	$V_{(GS)Q}$	-	-2.7	-	VDC	V_{DD} = 50 V, I_{DQ} = 500 mA, P_{IN} = 32 dBm
Saturated Drain Current	$\mathbf{I}_{ extsf{DC}}$	-	12	-	Α	$V_{DS} = 12 \text{ V, } V_{GS} = 2.0 \text{ V}$
RF Characteristics ¹						
Power Output at P _{OUT} @ 4.5 GHz	P _{OUT1}	41.0	42.8	-	dBm	V_{DD} = 50 V, I_{DQ} = 500 mA, P_{IN} = 32 dBm
Power Output at P _{OUT} @ 5.0 GHz	P _{OUT2}	41.0	43.3	-	dBm	$V_{_{\mathrm{DD}}}$ = 50 V, $I_{_{\mathrm{DQ}}}$ = 500 mA, $P_{_{\mathrm{IN}}}$ = 32 dBm
Power Output at P _{OUT} @ 6.0 GHz	Роитз	41.0	42.9	-	dBm	V_{DD} = 50 V, I_{DQ} = 500 mA, P_{IN} = 32 dBm
Drain Efficiency at P _{OUT} @ 4.5 GHz	η1	18.0	24.1	-	%	V_{DD} = 50 V, I_{DQ} = 500 mA, P_{IN} = 32 dBm
Drain Efficiency at P _{OUT} @ 5.0 GHz	η2	18.0	28.0	-	%	V_{DD} = 50 V, I_{DQ} = 500 mA, P_{IN} = 32 dBm
Drain Efficiency at P _{OUT} @ 6.0 GHz	η3	18.0	27.2	-	%	V_{DD} = 50 V, I_{DQ} = 500 mA, P_{IN} = 32 dBm
Output Mismatch Stress	VSWR	-	-	5:1	Ψ	No damage at all phase angles, $V_{\tiny DD} = 50$ V, $I_{\tiny DQ} = 500$ mA, $P_{\tiny IN} = 32$ dBm

Smal	I Signa	I RF C	haract	eristics

		S21			S11			S22		
Frequency	Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Conditions
0.02 GHz - 0.25 GHz	18.0	19.3	23.7	-	-4.1	-2.5	-	-8.5	-4.5	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA}$
0.25 GHz - 0.5 GHz	18.0	19.8	22.0	-	-6.8	-3.5	-	-8.9	-4.5	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA}$
0.5 GHz - 1.0 GHz	15.5	18.6	22.0	-	-15.3	-6.5	-	-6.7	-4.5	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA}$
1.0 GHz - 2.0 GHz	15.5	18.6	22.0	-	-15.3	-12.5	-	-6.7	-4.5	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA}$
2.0 GHz - 3.0 GHz	13.0	18.6	20.0	-	-15.3	-12.5	-	-6.0	-2.5	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA}$
3.0 GHz - 6.0 GHz	13.0	16.3	20.0	-	-14.2	-6.5	-	-5.3	-2.5	$V_{DD} = 50 \text{ V, } I_{DQ} = 500 \text{ mA}$

Notes

 $^{^{1} \ \}text{Refer to the Application Note on soldering at} \ \underline{\text{www.cree.com/products/wireless_appnotes.asp}}$

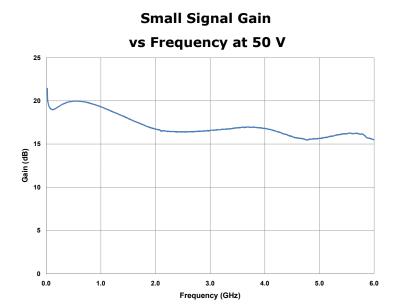
 $^{^{2}}$ Measured for the CMPA0060025F at P_{IN} = 32 dBm.

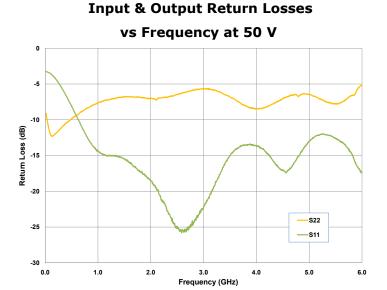
 $^{^{\}scriptscriptstyle 1}$ $P_{\scriptscriptstyle OUT}$ is defined as $P_{\scriptscriptstyle IN}$ = 32 dBm.

² The device will draw approximately 55-70 mA at pinch off due to the internal circuit structure.



Typical Performance



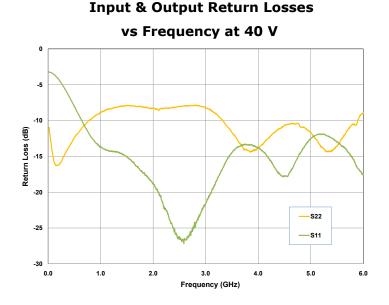


vs Frequency at 40 V

25
20
15
10
5
0.0
1.0
2.0
3.0
4.0
5.0
6.0

Frequency (GHz)

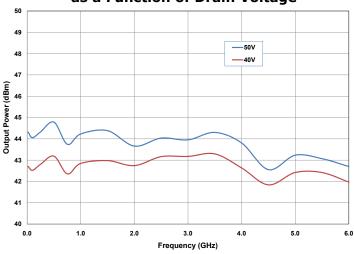
Small Signal Gain



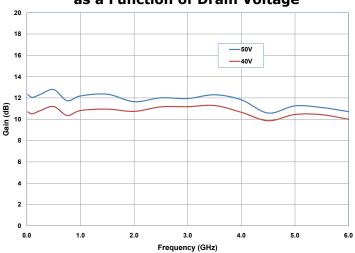


Typical Performance

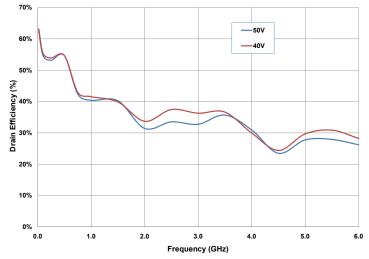
Output Power at $P_{IN} = 32 \text{ dBm vs Frequency}$ as a Function of Drain Voltage



Power Gain at $P_{IN} = 32 \text{ dBm vs Frequency}$ as a Function of Drain Voltage



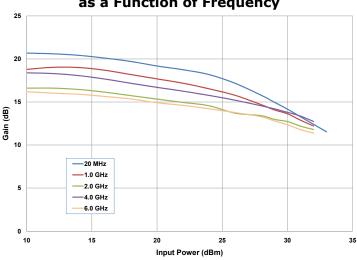
Drain Efficiency at $P_{IN} = 32 \text{ dBm vs Frequency}$ as a Function of Drain Voltage



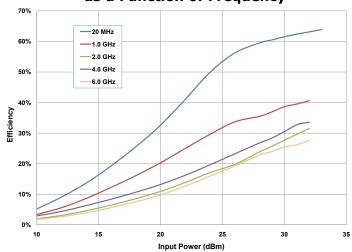


Typical Performance

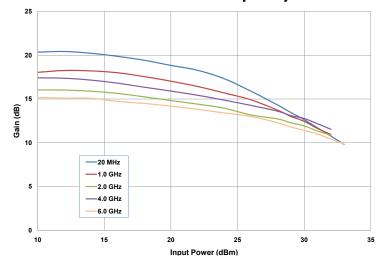
Gain vs Input Power at 50V as a Function of Frequency



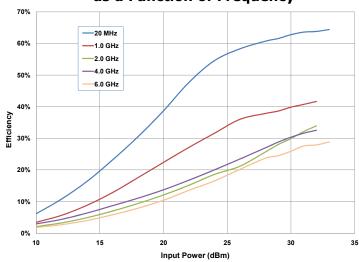
Efficiency vs Input Power at 50 V as a Function of Frequency



Gain vs Input Power at 40V as a Function of Frequency



Efficiency vs Input Power at 40 V as a Function of Frequency



www.cree.com/wireless



General Device Information

The CMPA0060025F is a GaN HEMT MMIC Power Amplifier, which operates between 20 MHz - 6.0 GHz. The amplifier typically provides 17 dB of small signal gain and 25 W saturated output power with an associated power added efficiency of better than 20 %. The wideband amplifier's input and output are internally matched to 50 Ohm. The amplifier requires bias from appropriate Bias-T's, through the RF input and output ports.

The CMPA0060025F is provided in a flange package format. The input and output connections are gold plated to enable gold bond wire attach at the next level assembly.

The measurements in this data sheet were taken on devices wire-bonded to the test fixture with 2 mil gold bond wires. The CMPA0060025F-TB and the device were then measured using external Bias-T's, (TECDIA: TBT-H06M20 or similar), as shown in Figure 2. The Bias-T's were included in the calibration of the test system. All other losses associated with the test fixture are included in the measurements.

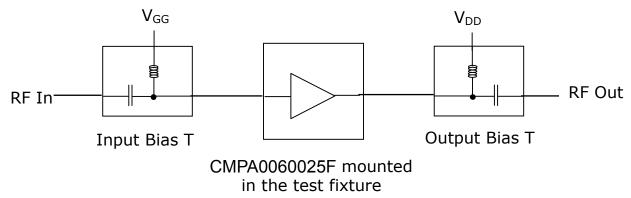
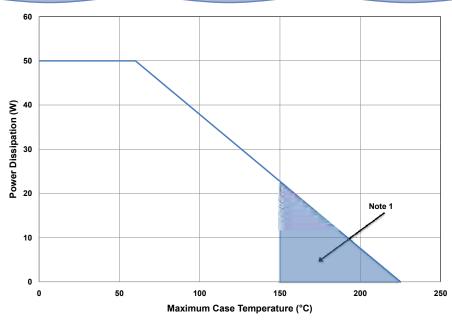


Figure 2. Typical test system setup required for measuring CMPA0060025F-TB



CMPA0060025F Power Dissipation De-rating Curve



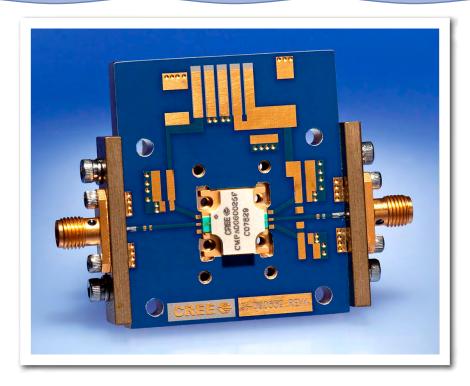
Note 1. Area exceeds Maximum Case Operating Temperature (See Page 2).

Electrostatic Discharge (ESD) Classifications

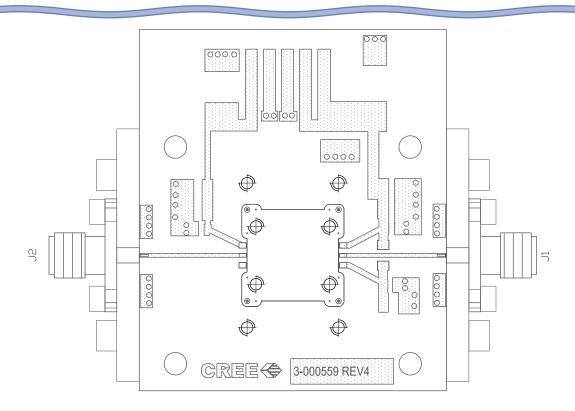
Parameter	Symbol	Class	Test Methodology
Human Body Model	НВМ	1A (> 250 V)	JEDEC JESD22 A114-D
Charge Device Model	CDM	II (200 < 500 V)	JEDEC JESD22 C101-C



CMPA0060025F-TB Demonstration Amplifier Circuit



CMPA0060025F-TB Demonstration Amplifier Circuit Outline



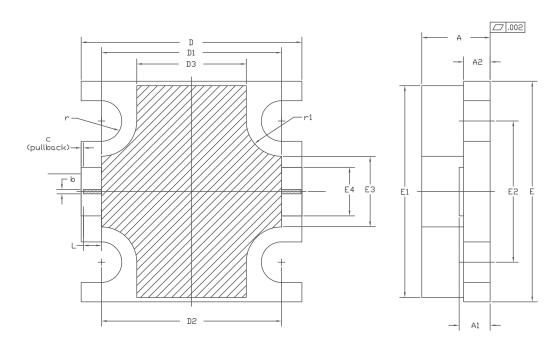


CMPA0060025F-TB Demonstration Amplifier Circuit Bill of Materials

Designator	Description	Qty
J1,J2	CONNECTOR, SMA, AMP1052901-1	2
-	PCB, TACONIC, RF-35-0100-CH/CH	1
Q1	CMPA0060025F	1

Notes

Product Dimensions CMPA0060025F (Package Type - 780019)



NULLS

1. DIMENSIONING AND TOLERANICING PER ANSI Y14.5M, 1982.

2. CONTROLLING DIMENSION: INCH.

3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020' BEYOND EDGE OF LID.

4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.

5. ALL PLATED SURFACES ARE NI/AU

	INCHES		MILLIN	ETERS	NOTE
DIM	MIN	MAX	MIN	MAX	NOTE
Α	0.148	0.162	3.76	4.12	_
A1	0.066	0.076	1.67	1.93	_
A2	0.056	0.064	1.42	1.63	_
b	0.0	09	0.	24	×2
С	0.0	05	0.	13	x2
D	0.495	0.505	12.57	12.83	_
D1	0.403	0.413	10.23	10.49	_
D2	0.4	80	10	_	
D3	0.243	0.253	6.17	6.43	_
E	0.495	0.505	12.57	12.83	_
E1	0.475	0.485	12.06	12.32	_
E2	0.3	20	8.13		_
E3	0.155	0.165	3.93	4.19	_
E4	0.105	0.115	2.66	2.92	_
L	0.0	41	1.	x2	
r	R0.0)46	R1	x4	
r1	R0.0	080	R2	.03	x4

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¹The CMPA0060025F is connected to the PCB with 2.0 mil Au bond wires.

² An external bias T is required.



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